

### Supplementary Information

#### **FeVSb-based amorphous films with ultra-low thermal conductivity and high ZT: a potential material for thermoelectric generators**

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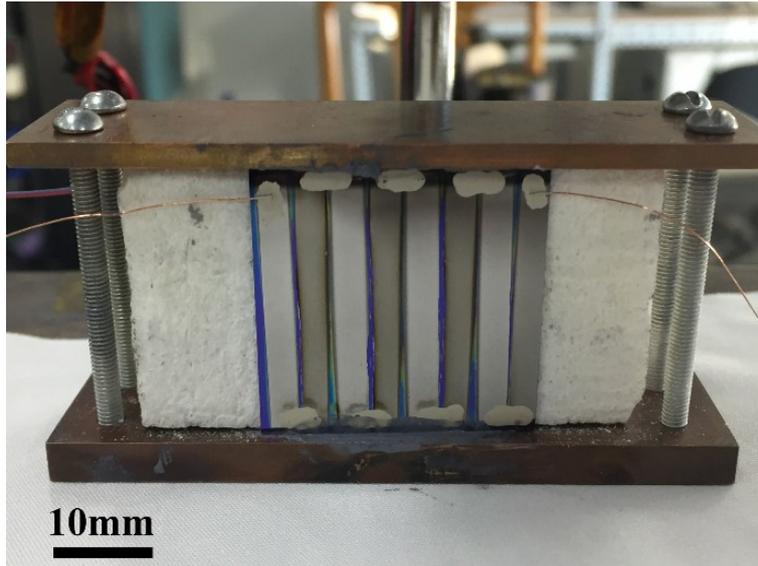
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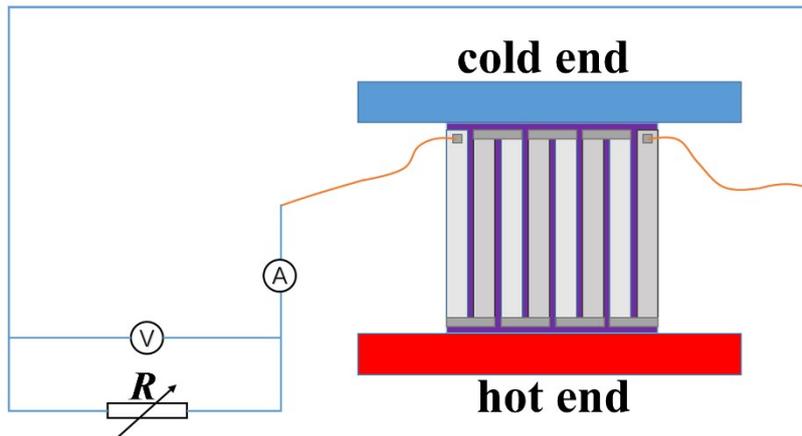
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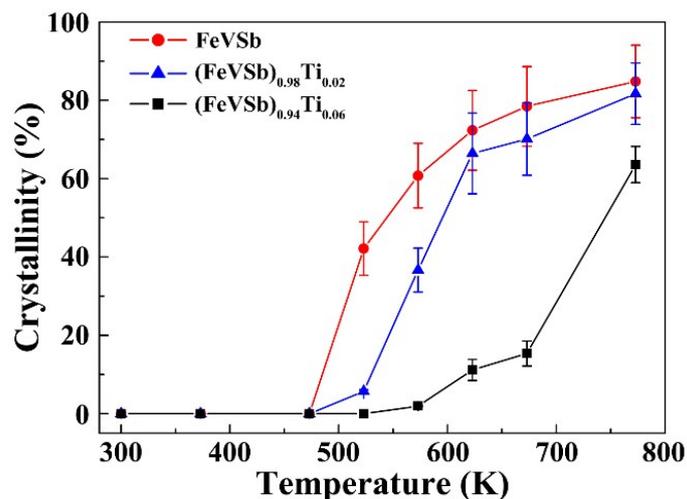
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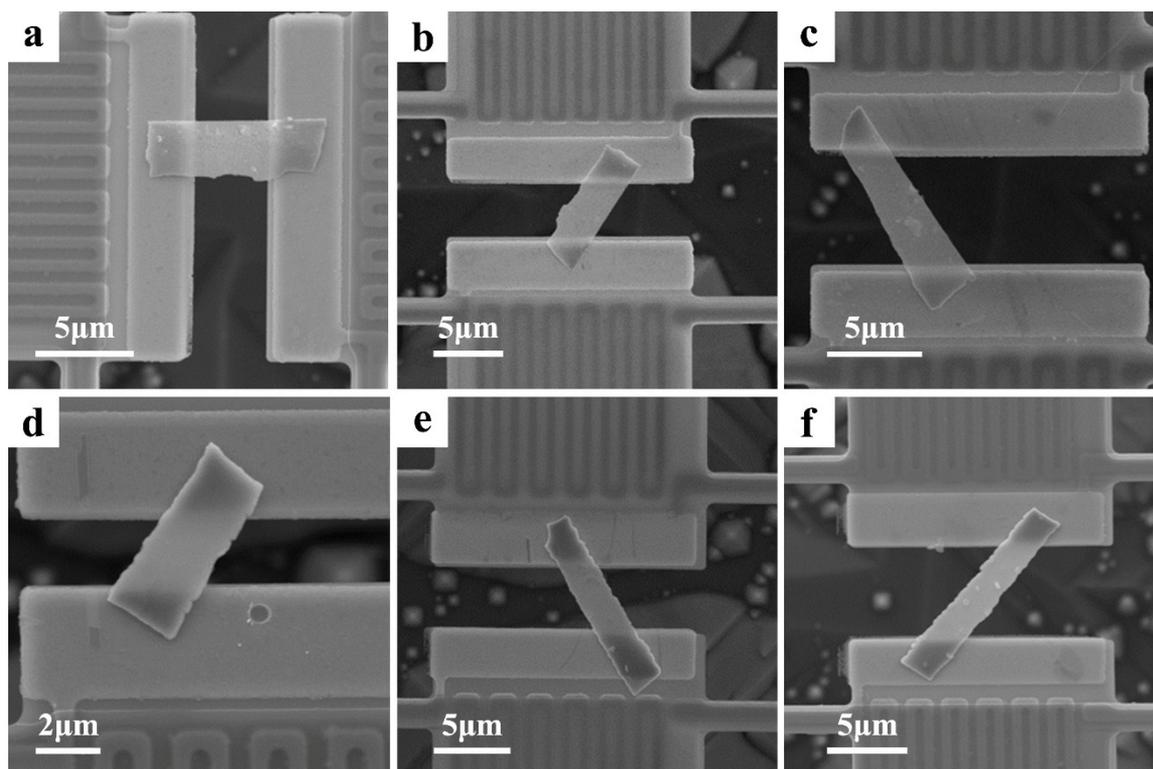
**Figure S1.** Photograph of the planar TEG placed between two Cu plates.



**Figure S2.** Circuit diagram to measure the TEG performance.



**Figure S3.** Crystallinity of FeVSb, (FeVSb)<sub>0.98</sub>Ti<sub>0.02</sub>, and (FeVSb)<sub>0.94</sub>Ti<sub>0.06</sub> samples based on the in situ high temperature XRD data with the peak fitting method.



**Figure S4.** SEM images of the FeVSb (a–c) and (FeVSb)<sub>0.94</sub>Ti<sub>0.06</sub> (d–f) samples with different suspended lengths  $L_s$  placed onto the microdevices, which are used to measure the thermal conductivity by the suspended thermal bridge method. (a)  $L_s=4.10$   $\mu\text{m}$ . (b)  $L_s=4.94$   $\mu\text{m}$ . (c)  $L_s=7.59$   $\mu\text{m}$ . (d)  $L_s=2.58$   $\mu\text{m}$ . (e)  $L_s=5.06$   $\mu\text{m}$ . (f)  $L_s=8.56$   $\mu\text{m}$ .

## Uncertainty Analysis of Thermal Conductivity Measurement

Thermal conductivity is extracted from the measurements on the same sample with three different suspended lengths. For a uniform sample, the measured  $R_{tot}$  can be written as:

$$R_{tot} = R_c + R_{s/L} \times L_s, \quad (1)$$

where  $R_c$  is the contact thermal resistance between the sample and two membranes,  $R_{s/L}$  is the thermal resistance per unit length, and  $L_s$  is the suspended length.  $R_c$  can be assumed as a constant in different measurements when the sample is fully thermalized with membranes at two ends according to the fin heat transfer model.<sup>1</sup> The insets of Figures 9a and 9b show that there is a good linear relationship between the  $R_{tot}$  and  $L_s$  for both samples, which in return verifies the assumption that the  $R_c$  is a constant in different measurements. The slope of the linear lines in the insets of Figures 9a and 9b stands for the  $R_{s/L}$ , thus the thermal conductivity  $\kappa$  is determined by

$$\kappa = 1/(w \cdot t \cdot R_{s/L}), \quad (2)$$

where  $w$  and  $t$  are the width and thickness of the sample, respectively.

The relative uncertainty in the extracted thermal conductivity can be calculated by

$$\frac{\delta\kappa}{\kappa} = \sqrt{\left(\frac{\delta R_{s/L}}{R_{s/L}}\right)^2 + \left(\frac{\delta w}{w}\right)^2 + \left(\frac{\delta t}{t}\right)^2}, \quad (3)$$

where  $\delta R_{s/L}$ ,  $\delta w$ , and  $\delta t$  are the uncertainties in the thermal resistance per unit length, width, and thickness, respectively. The width  $w$  is determined from the SEM images and its uncertainty  $\delta w$  is estimated as 5 nm. The thickness  $t$  is measured by AFM and its uncertainty  $\delta t$  is estimated as 5 nm.

From the measurements on the thermal resistances ( $R_{tot}$ ) at three different suspended lengths ( $L_s$ ), the  $R_{s/L}$  is determined by the least squares fitting,

$$R_{s/L} = \frac{n \sum_{i=1}^n L_{s,i} R_{tot,i} - \sum_{i=1}^n L_{s,i} \sum_{i=1}^n R_{tot,i}}{n \sum_{i=1}^n L_{s,i}^2 - \left( \sum_{i=1}^n L_{s,i} \right)^2}, \quad (4)$$

where  $n$  is 3 in our measurements. Then, the uncertainty in  $R_{s/L}$  is estimated by the following expression:<sup>2</sup>

$$\delta R_{s/L} = \sqrt{\sum_{i=1}^n \left( \frac{\partial R_{s/L}}{\partial R_{tot,i}} \right)^2 \delta R_{tot,i}^2 + \sum_{i=1}^n \left( \frac{\partial R_{s/L}}{\partial L_{s,i}} \right)^2 \delta L_{s,i}^2}, \quad (5)$$

where  $\delta R_{tot,i}$  and  $\delta L_{s,i}$  are the uncertainties in the measured thermal resistances and the suspended lengths, respectively. The relative uncertainty in the measured thermal resistance ( $\delta R_{tot,i}/R_{tot,i}$ ) is evaluated using the Monte Carlo method and is less than 5% for the measured samples. The suspended length  $L_s$  is measured from the SEM images, and the error  $\delta L_{s,i}$  is estimated to be 10 nm.

With the uncertainty data listed above, the uncertainty in the thermal conductivity  $\delta \kappa$  can be calculated with Eq. (3). For example, the  $\delta \kappa$  is 0.209 and 0.094  $\text{Wm}^{-1}\text{K}^{-1}$  for the FeVSb and  $(\text{FeVSb})_{0.94}\text{Ti}_{0.06}$  films at 300 K, respectively.

#### References:

1. C. H. Yu, S. Saha, J. H. Zhou, L. Shi, A. M. Cassell, B. A. Cruden, Q. Ngo and J. Li, *Journal of Heat Transfer-Transactions of the Asme*, 2006, **128**, 234-239.
2. H. W. Coleman and W. G. Steele, *Experimentation, Validation, and Uncertainty Analysis for Engineers, Third Edition*, 2009.